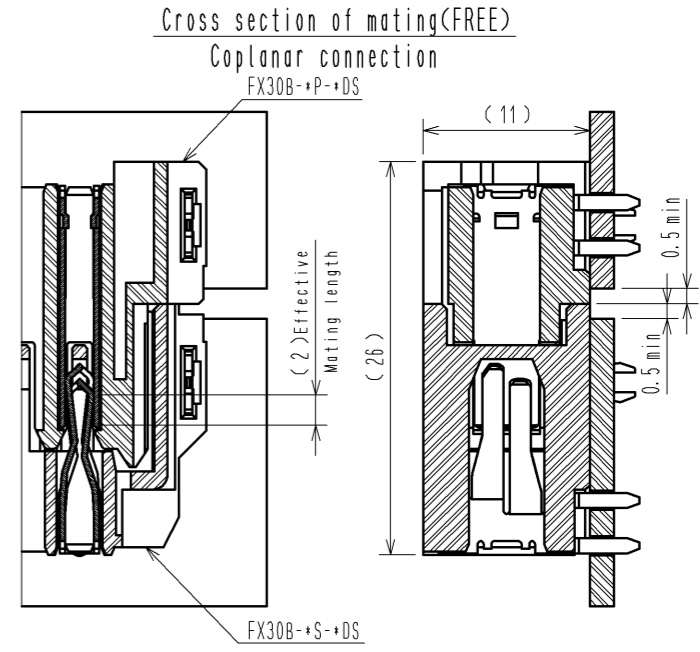
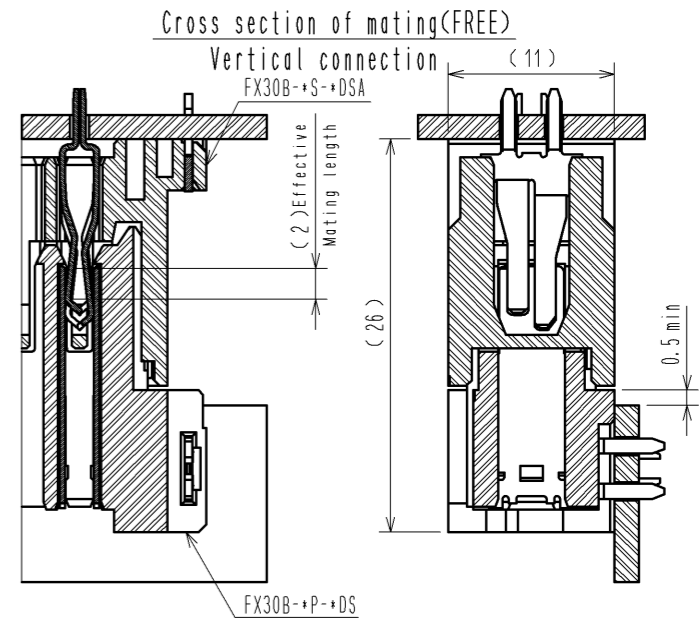
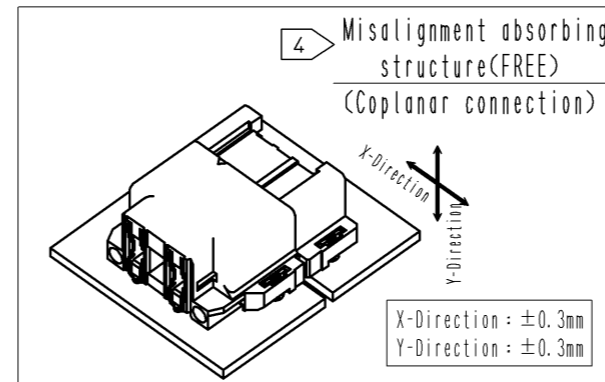
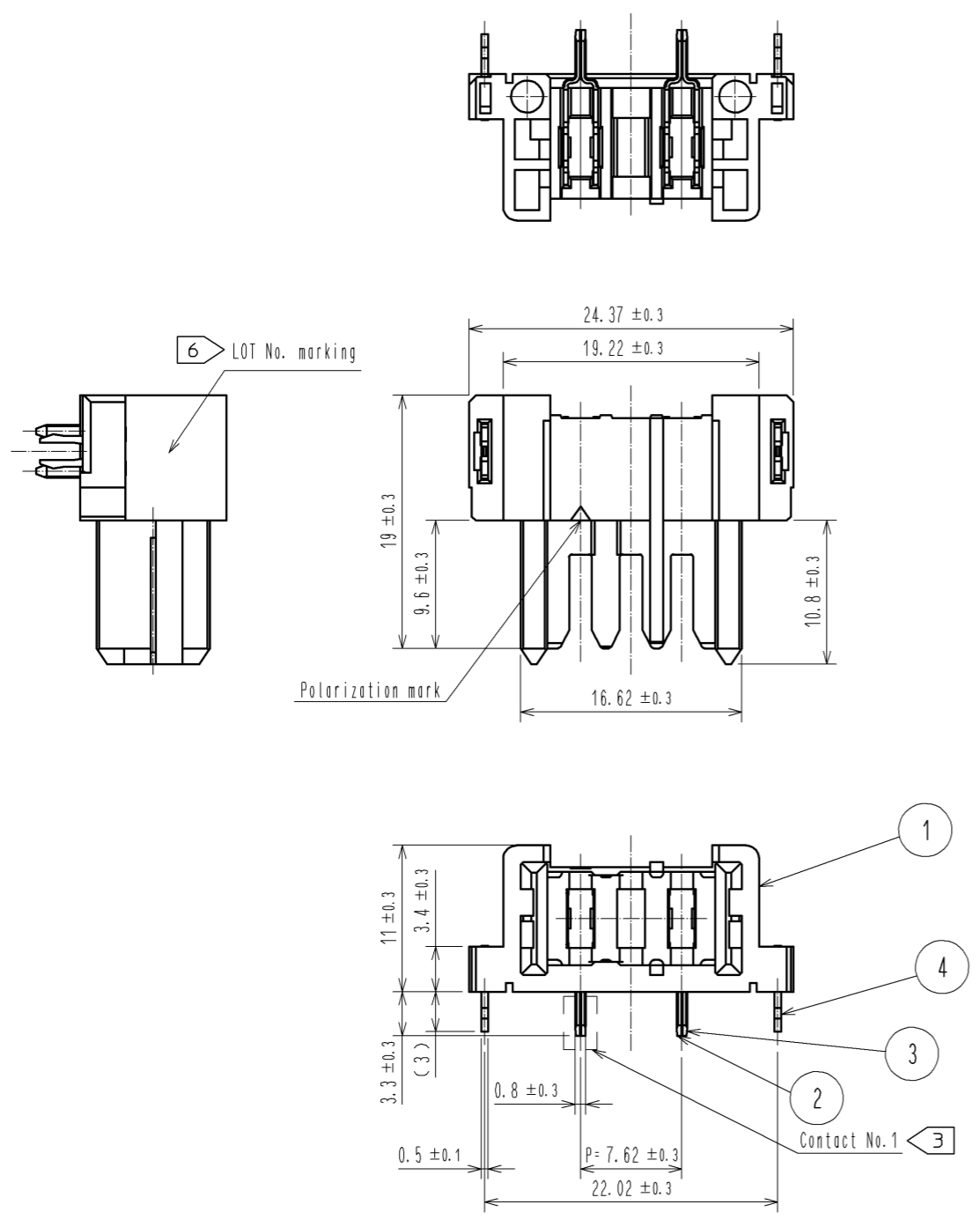


APPLICABLE STANDARD				
RATING	Operating Temperature Range	-55 °C to 105 °C ⁽¹⁾	Storage Temperature Range	-10 °C to 60 °C ⁽²⁾
	Voltage	600 V AC/DC	Storage Humidity Range	40 % to 70 % ⁽²⁾
	Current	15A	Operating Humidity Range	Relative Humidity 85% max (Not dewed)
SPECIFICATIONS				
ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
General Examination	Visually and by measuring instrument.	According to drawing.	×	×
Marking	Confirmed visually.		×	×
ELECTRIC CHARACTERISTICS				
Contact Resistance	10 mA(DC or 1000Hz)	2 mΩ MAX.	×	—
Insulation Resistance	1000 V DC.	1000 MΩ MIN.	×	—
Voltage Proof	1800 V AC for 1 min.	No flashover or breakdown.	×	—
MECHANICAL CHARACTERISTICS				
Insertion and Withdrawal Forces	Measured by applicable connector.	Insertion Force: 10 N MAX. Withdrawal Force: 0.4 N MIN.	×	—
Mechanical Operation	100 times insertions and extractions.	① Contact Resistance: 5 mΩ MAX. ② No damage, crack and looseness of parts.	×	—
Vibration	Frequency 10 to 55 to 10Hz, approx 5min Single amplitude : 0.75 mm, 10 cycles for 3 axial directions.	① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.	×	—
Shock	490 m/s ² , duration of pulse 11 ms, 3 times to both directions in 3 axial directions.		×	—
ENVIRONMENTAL CHARACTERISTICS				
Damp Heat (Steady State)	Exposed at 40±2 °C, 90 ~ 95 %, 96 ±4h.	① Contact Resistance: 5mΩ MAX. ② Insulation Resistance: 1000 MΩ MIN. ③ No damage, crack and looseness of parts.	×	—
Rapid Change of Temperature	Temperature -55 → +105 °C Time 30 → 30 min. under 5 cycles. (Relocation time to chamber: within 2~3 MIN)		×	—
Dry heat	Exposed at +105±2°C for 96±4h.		×	—
Cold	Exposed at -55±2°C for 96±4h.		×	—
Sulfur Dioxide	Exposed at 25±2°C, 75±5%RH, 25 PPM for 96h±4h.	① Contact Resistance: 5mΩ MAX. ② No defect such as corrosion which impairs the function of connector.	×	—
Resistance to Soldering Heat	Solder bath : Solder temperature 260±5°C for immersion, duration 10±1sec. Soldering irons : 380°C MAX. for 10 sec.	No deformation of case of excessive looseness of the terminal.	×	—
Solderability	Soldered at solder temperature 240±3°C for immersion, duration 3 sec.	A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.	×	—
COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△				
REMARKS ⁽¹⁾ Include temperature rise caused by current-carrying. ⁽²⁾ "Storage" means a long-term storage state for the unused product before assembly to PCB.		APPROVED	HS. OKAWA	14. 09. 12
		CHECKED	KN. SHIBUYA	14. 09. 11
		DESIGNED	DK. AIMOTO	14. 09. 11
		DRAWN	DK. AIMOTO	14. 09. 11
Unless otherwise specified, refer to JIS-C-5402, IEC60512.				
Note QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.		ELC4-359163-00
HRS	SPECIFICATION SHEET		PART NO.	FX30B-2P-7. 62DS
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL570-3404-8-00
			△	1/1



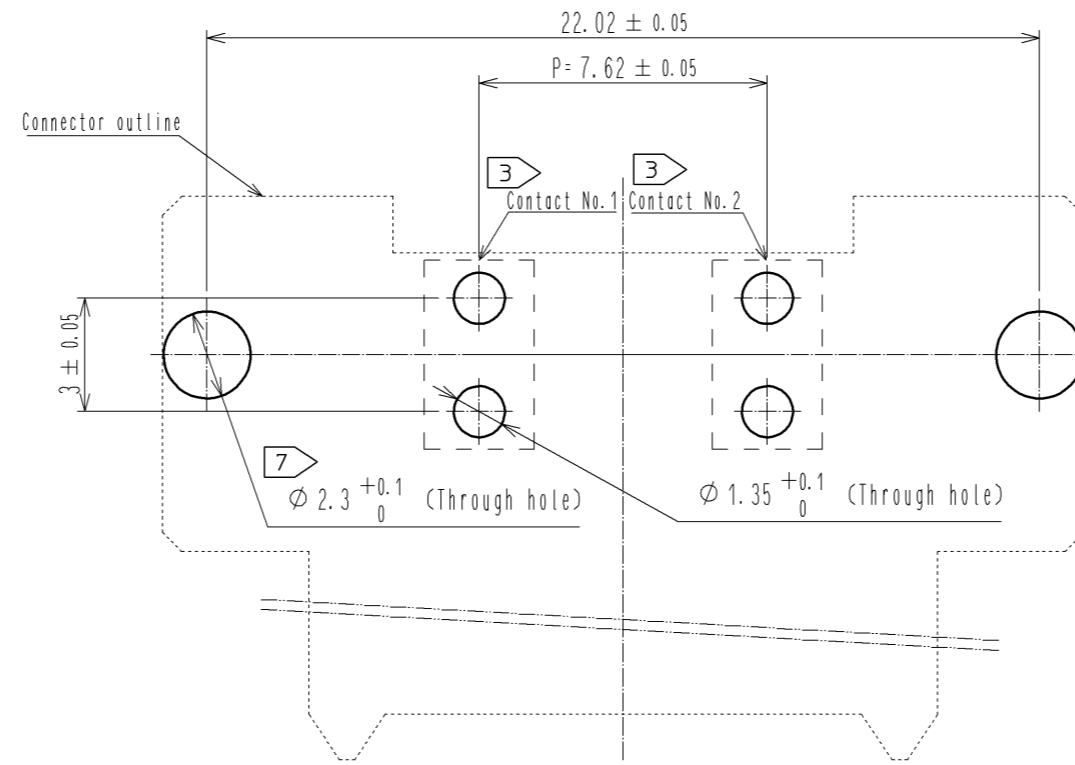
- NOTE
- ① This product is packaged in tray. (24pcs/tray)
 - ② Blemish and hit mark can be occurred through out the manufacturing process which doesn't affect quality level. Also, black spot could be observed on the surface of housing.
 - ③ For the contact NO., adjacent two pairs of leads placed back-to-back (4 leads in total) compose one line.
 - ④ Misalignment absorbing range: ±0.3mm max.
 - ⑤ The dimension in parentheses are for references.
 - ⑥ Lot NO. is indicated at either one of the position as shown.
 - ⑦ Pay attention to the recommended PCB thickness and finished through-hole dimensions. Low retention force to PCB could induce angled mounting due to the unbalanced center of the connector.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
2	Copper alloy	Contact area: Gold-plating 0.1μm Lead area: Tin-plating 1.0μm Under plating: Nickel 1.0μm		3	Copper alloy	Contact area: Gold-plating 0.1μm Lead area: Tin-plating 1.0μm Under plating: Nickel 1.0μm	
1	Polyamide	Black UL94V-0		4	Phosphor bronze	Tin-plating 3.0μm Under plating: Nickel 1.0μm	
				5	Polystyrene		

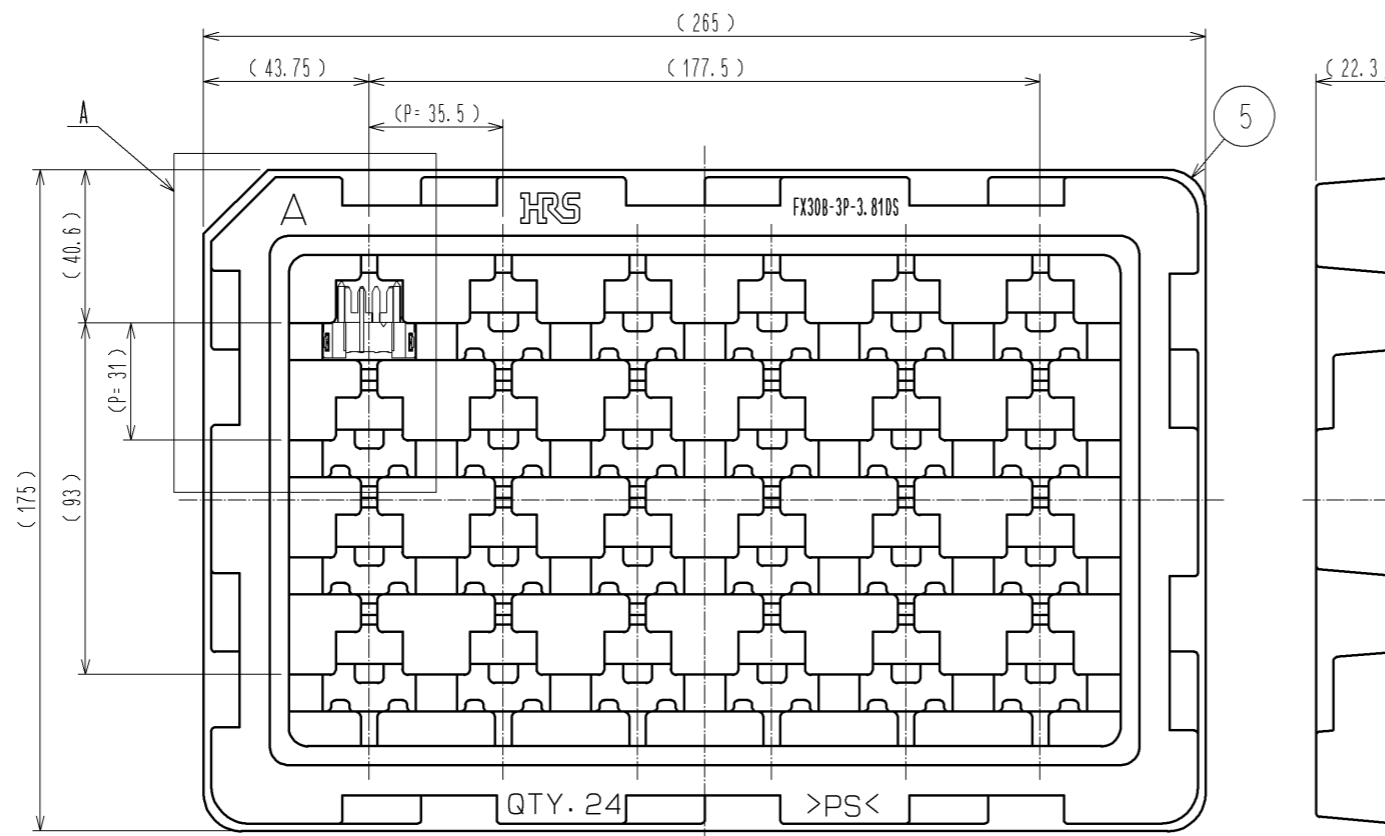
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2 : 1	△	APPROVED : HS. OKAWA 14.09.12 CHECED : KN. SHIBUYA 14.09.12 DESIGNED : DK. AIMOTO 14.09.12 DRAWN : DK. AIMOTO 14.09.12			

DRAWING NO.	PART NO.	CODE NO.
EDC3-359163-00	FX30B-2P-7.62DS	CL570-3404-8-00

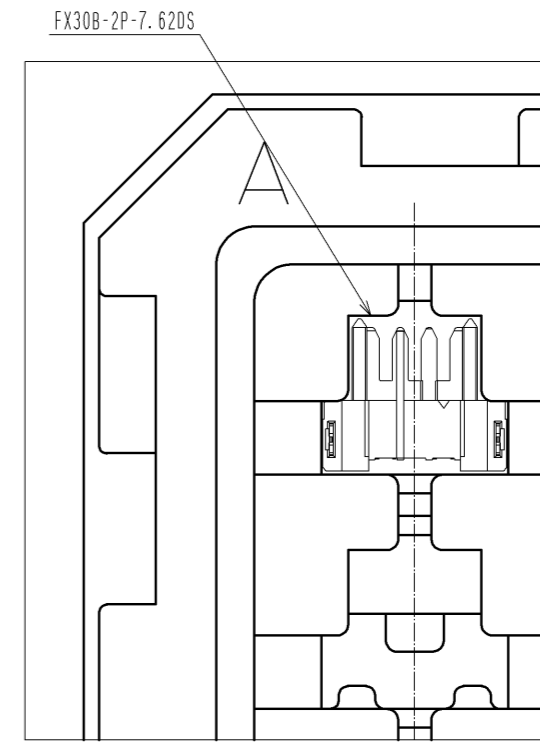
Recommended hole pattern dimension of PCB(5:1)
(Connector mounting side, PCB thickness: t=1.6mm) $\triangleleft 7$



$\triangleleft 1$ Drawing for packaging(1:2)



A(1:1)



HRS	DRAWING NO.	EDC3-359163-00	$\triangleleft 2/2$
	PART NO.	FX30B-2P-7.62DS	
	CODE NO.	CL570-3404-8-00	